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IMAPS Device Packaging Conference 2026 to Focus on AI, Chiplets, and Advanced Integration

The 22nd Annual Device Packaging Conference (DPC 2026), organized by the International Microelectronics Assembly and Packaging Society (IMAPS), will take place March 2–5, 2026, in Phoenix, Arizona, at the Sheraton Grand at Wild Horse Pass. The international conference is expected to draw a broad cross-section of the semiconductor packaging community, as advanced packaging continues to play a central role in enabling AI, high-performance computing, and heterogeneous integration.

DPC 2026 is positioned as one of the industry's most comprehensive technical forums focused on device-level packaging and microelectronics assembly, with a program designed to address both emerging research and manufacturing-ready solutions. Attendees are expected to include scientists, process and manufacturing engineers, product engineers, researchers, academics, and industry professionals spanning business development through sales and marketing.

Packaging at the Center of System Innovation

As scaling at the transistor level becomes more challenging, packaging has increasingly become a primary driver of system performance, power efficiency, and integration density. DPC 2026 reflects this shift, with a technical program that emphasizes device-aware packaging approaches and the convergence of front-end device design with back-end assembly.

The conference will feature a four-track technical program covering topics such as chiplets and heterogeneous integration, advanced substrates and interposers, fan-out wafer- and panel-level packaging, hybrid bonding, thermal management, reliability, and emerging photonic and power packaging technologies. An interactive poster session, an evening panel discussion, and an embedded Global Business Council Plenary Session are also planned.

Keynotes Address AI Workloads and Packaging Challenges

Four keynote presentations will anchor the technical program, highlighting the role of advanced packaging in next-generation computing systems.

Sandeep Razdan, Director of the Advanced Technology Group at NVIDIA, will address Silicon Photonics Advanced Packaging for Data Center AI Workloads, examining packaging strategies to support bandwidth density and energy efficiency in AI data centers.

Thorsten Meyer, Distinguished Engineer at Infineon, will present Power Packaging for AI/Data Center from Grid to Core, focusing on power delivery challenges across increasingly complex system architectures.

Raja Swaminathan, Corporate Vice President of Heterogeneous Integration Technologies at AMD, will discuss The Future of AI Hardware Enabled by Advanced Packaging, highlighting how packaging technologies are shaping system-level performance and scalability.

Yoshiki Takahashi, Deputy General Manager of the Advanced Semiconductor Packaging Group at AGC, will present Overcoming Critical Challenges in Glass Core Substrates for Next-Generation Chiplet and CPO Applications, addressing materials and process challenges for emerging substrate platforms.

Professional Development and Industry Participation

The conference will open on March 2 with a full day of professional development courses, offering in-depth instruction on topics including co-packaged optics, substrates and interposers, fan-out packaging, hybrid bonding, thermal management, failure analysis, and cost modeling for advanced packaging technologies.

Industry participation is expected to be strong, with the DPC 2026 exhibit hall already sold out. Exhibitors include semiconductor packaging service providers, equipment suppliers, materials manufacturers, and related organizations, reflecting continued investment in advanced packaging infrastructure and capabilities.

A Focused Forum for the Packaging Community

With its emphasis on device-level challenges, applied research, and manufacturability, IMAPS DPC 2026 offers a targeted forum for the advanced packaging community at a time when packaging is increasingly defining system performance. As AI, chiplet architectures, and heterogeneous integration move further into high-volume production, DPC 2026 is expected to provide timely insight into the technologies and strategies shaping the next phase of semiconductor integration.